



Product Change Notification

Change Notification #: 117501 - 00
Change Title: Intel® Compute Module HNS2600BPQR, PCN 117501-00, Product Design, Design Improvement for Power Cable Plastic Cover
Date of Publication: March 20, 2020

Key Characteristics of the Change:
Product Design

Forecasted Key Milestones:

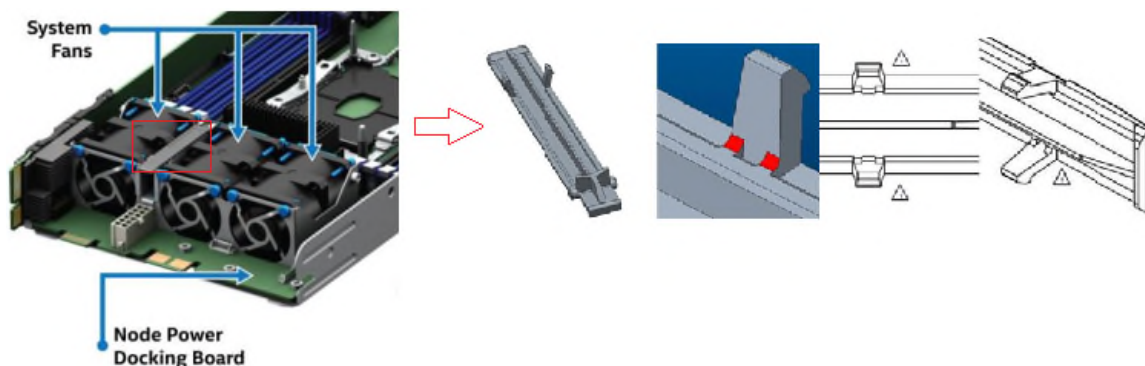
Date Customer Must be Ready to Receive Post-Conversion Material:*	April 6, 2020
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing an improvement on plastic cover placed upon Intel® Compute Module Power Cables, Design improvement consists of the following:

- Increase the thickness of hooks by 0.3 mm for both sides
- Reduce 3mm to the rib down the "T"



Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason, Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
HNS2600BPQR	985900	K36258-003	K36258-004

PCN Revision History:

Date of Revision:

March 20, 2020

Revision Number:

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Reason:

Originally Published PCN



Product Change Notification

117501 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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